

IN THE CLAIMS

Please add claims 31-38.

Please amend the following claims which are pending in the present application:

Listing of the Claims:

1-22. (Cancelled)

23. (Currently Amended) A system comprising:

a substrate;

a component coupled to said substrate; and;

a composition of magnetic material particles and a polymer-based material coupled to said component and said substrate, wherein the dimensions of the magnetic material particles are approximately one micron by two microns by ten microns.

24. (Original) The system of claim 23 further comprising screen pads coupled to said substrate.

25. (Original) The system of claim 23 wherein said magnetic material particles include a conductive path between said component and said substrate.

26. (Original) The system of claim 23 wherein said substrate is selected from a group consisting of printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

27. (Original) The system of claim 23 wherein said composition is comprised of approximately 40 percent by weight of the polymer-based material and approximately 60 percent by weight of the magnetic material particles.

28. (Original) The system of claim 23 wherein said magnetic material particles are acicular shaped.

29. (Original) The system of claim 23 wherein said polymer-based material is photo-resist material.

30. (Original) The system of claim 23 wherein a coefficient of thermal expansion of the polymer-based material is approximately equal to a coefficient of thermal expansion of the substrate.

31. (New) A system comprising:
a substrate;
a component coupled to said substrate; and;

a composition of magnetic material particles and a polymer-based material coupled to said component and said substrate, wherein said magnetic material is selected from the group consisting of barium strontium titanate, strontium tantalum oxide, and perovskites.

32. (New) The system of claim 31 further comprising screen pads coupled to said substrate.

33. (New) The system of claim 31 wherein said magnetic material particles include a conductive path between said component and said substrate.

34. (New) The system of claim 31 wherein said substrate is selected from a group consisting of printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

35. (New) The system of claim 31 wherein said composition is comprised of approximately 40 percent by weight of the polymer-based material and approximately 60 percent by weight of the magnetic material particles.

36. (New) The system of claim 31 wherein said magnetic material particles are acicular shaped.

37. (New) The system of claim 31 wherein said polymer-based material is photo-resist material.

38. (New) The system of claim 31 wherein a coefficient of thermal expansion of the polymer-based material is approximately equal to a coefficient of thermal expansion of the substrate.